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Product data sheet

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SOD-123FL

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * High surge current capability

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Terminals: Solder plated, solderable per MIL-STD-202F, method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

	P/N	DSR1A S1A	DSR1B S1B	DSR1D S1D	DSR1G S1G	DSR1J S1J	DSR1K S1K	DSR1M S1M	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _L = 100°C (NOTE 1)	I _(AV)	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	25.0							A
Maximum instantaneous forward voltage at 1.0A	V _F	1.1							V
Maximum DC reverse current at rated DC blocking voltage T _A = 25 C T _A = 125 C	I _R	10.0 50.0							μA
Typical junction capacitance (NOTE 2)	C _J	4							pF
Typical thermal resistance (NOTE 3)	R _{θJA}	95							°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance from Junction to Ambient.

FIG.1-TYPICAL FORWARD CHARACTERISTICS

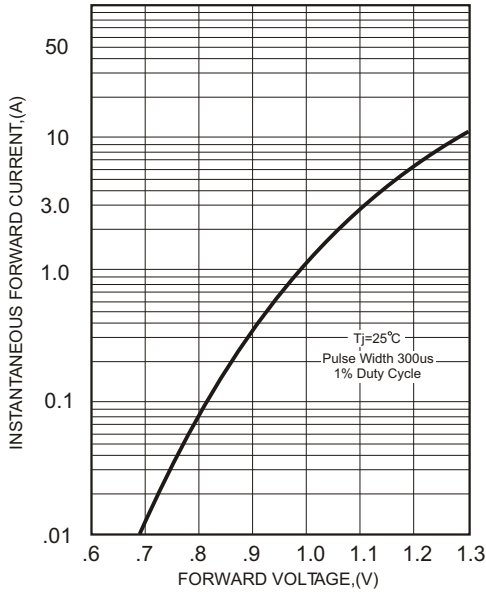


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

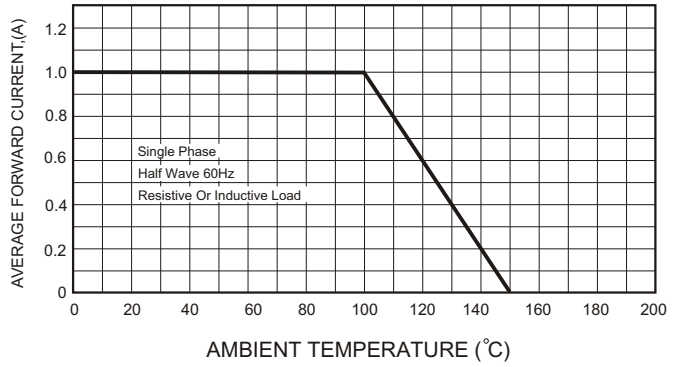


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

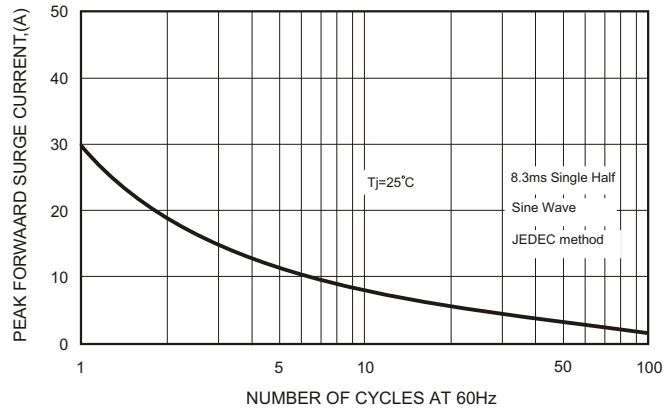


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

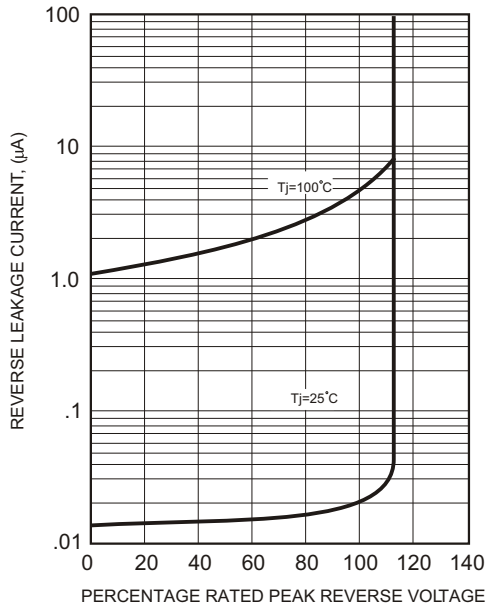
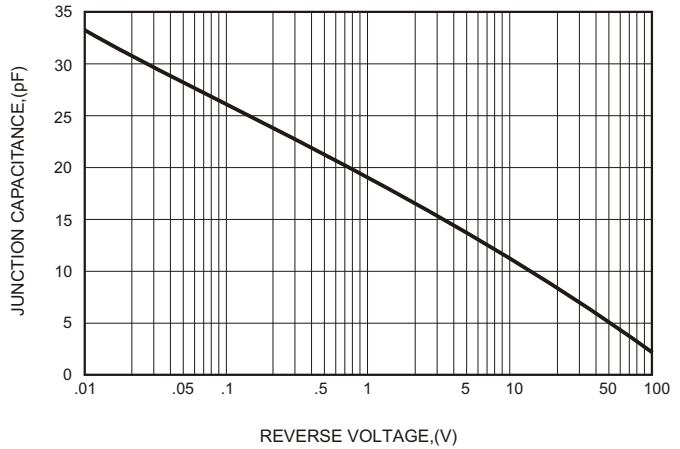
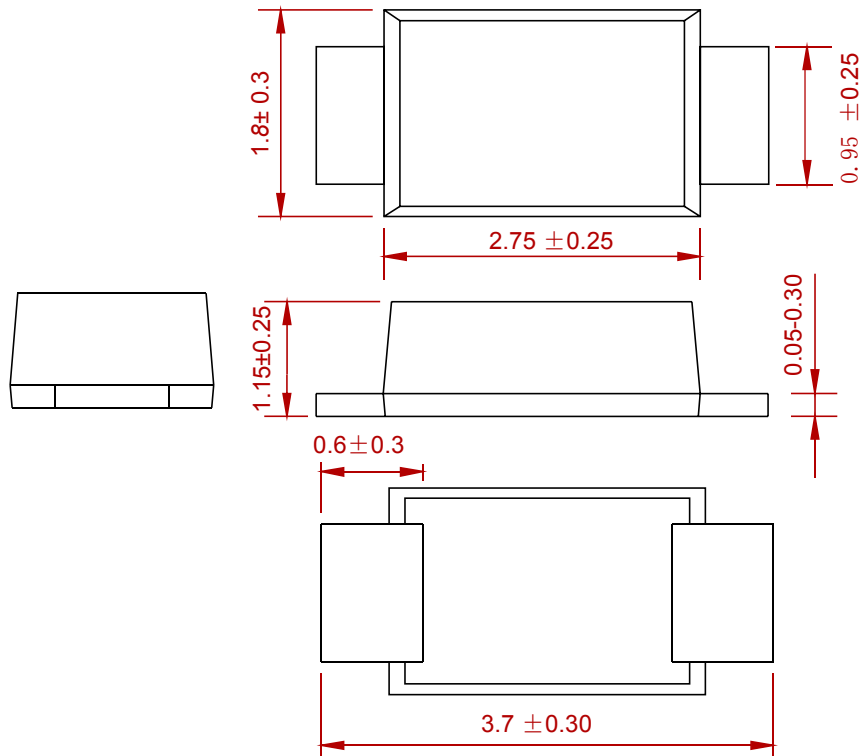


FIG.5-TYPICAL JUNCTION CAPACITANCE

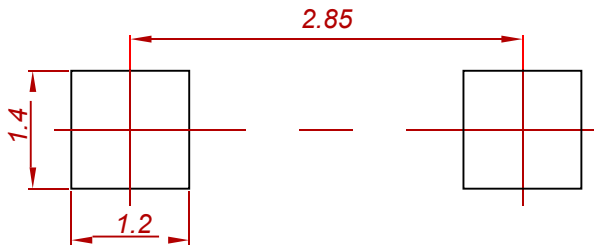


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DSR1A TRHU DSR1M	SOD-123FL	3000

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